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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Michiyasu KOMATSU, et al.

SERIAL NO.: NEW U.S. PCT APPLICATION

FILED: HEREWITH

INTERNATIONAL APPLICATION NO.: PCT/JP04/17531 INTERNATIONAL FILING DATE: November 18, 2004

FOR: HIGH THERMALLY CONDUCTIVE ALUMINUM NITRIDE SINTERED

**PRODUCT** 

(0)

## **REQUEST FOR PRIORITY UNDER 35 U.S.C. 119** AND THE INTERNATIONAL CONVENTION

Commissioner for Patents Alexandria, Virginia 22313

Sir:

In the matter of the above-identified application for patent, notice is hereby given that the applicant claims as priority:

**COUNTRY** 

APPLICATION NO

DAY/MONTH/YEAR

21 November 2003

Japan

2003-392464

Certified copies of the corresponding Convention application(s) were submitted to the Receipt of the certified

International Bureau in PCT Application No. PCT/JP04/17531. copy(s) by the International Bureau in a timely manner under PCT Rule 17.1(a) has been acknowledged as evidenced by the attached PCT/IB/304.

> Respectfully submitted, OBLON, SPIVAK, McCLELLAND,

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